

## ESD3V3D8B

### Description

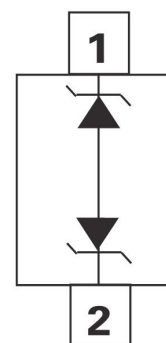
The ESD3V3D8B in a SOD-882 package and will protect bidirectional line. These devices are designed to replace multilayer varistors (MLVs) in portable applications such as cell phones, notebook computers, and PDA's. They offer superior electrical characteristics such as lower clamping voltage and no device degradation when compared to MLVs, The ESD3V3D8B are designed to protect sensitive semiconductor components from damage or upset due to electrostatic discharge (ESD), and other voltage induced transient events.



### Feature

- Case : SOD882 package
- Low clamping voltage
- Low Leakage current
- Peak Power up to 150 Watts @ 8 x 20  $\mu$ s Pulse
- Response Time is Typically < 1.0 ns
- IEC61000 4 2 Level 4 ESD Protection

### Schematic & PIN Configuration



### Applications

- Cellular phones
- Portable devices
- Digital cameras
- Power supplies

### Absolute Maximum Ratings

Parameter	Symbol	Value	Units
IEC61000-4-2 (Contact)	$V_{ESD}$	8	kV
IEC61000-4-2 (Air)	$V_{ESD}$	15	kV
Lead Soldering Temperature	$T_L$	260 (10 sec)	$^{\circ}$ C
Operating Temperature	$T_{op}$	-40 to 125	$^{\circ}$ C
Storage Temperature Range	$T_{STG}$	-55 to 155	$^{\circ}$ C
Maximum junction temperature	$T_j$	150	$^{\circ}$ C
Peak Pulse Power ( $t_p = 8/20s$ )	$P_{pk}$	150	W

**Electrical Characteristics (T = 25° C)**

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Reverse Stand-off Voltage	$V_{RWM}$				3.3	V
Reverse Breakdown Voltage	$V_{BR}$	$I_t = 1\text{mA}$	5			V
Reverse Leakage Current	$I_R$	$V_R = V_{RWM}$			1	$\mu\text{A}$
Clamping Voltage	$V_C$	$I_{PP}=5\text{A}, t_p = 8/20\mu\text{s}$		8.4		V
Peak pulse Current	$I_{PP}$	$t_p = 8/20\mu\text{s}$			11.2	A
Junction Capacitance	$C_J$	$V_R=0\text{V}, f = 1\text{MHz}$		25		pF

**Rating & Characteristic Curves**

Figure 1 - Electrical Parameter

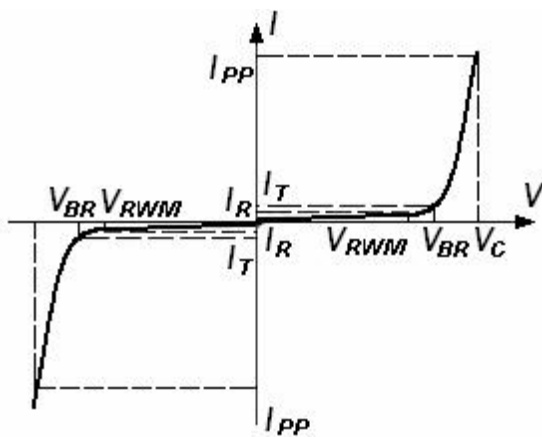


Figure 2- Pulse Waveform

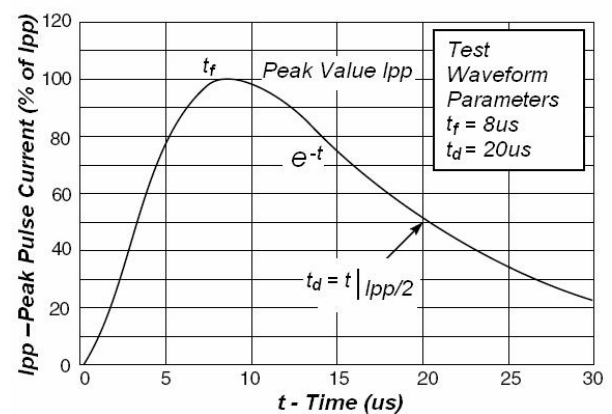
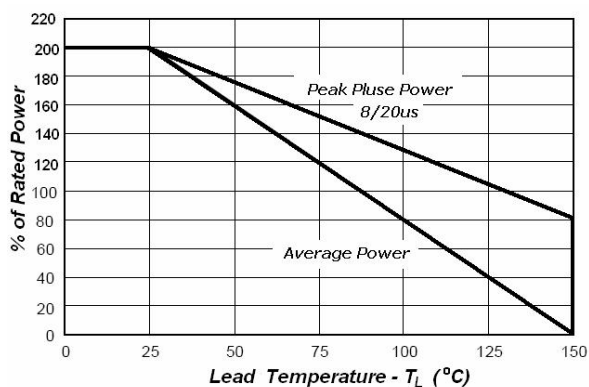
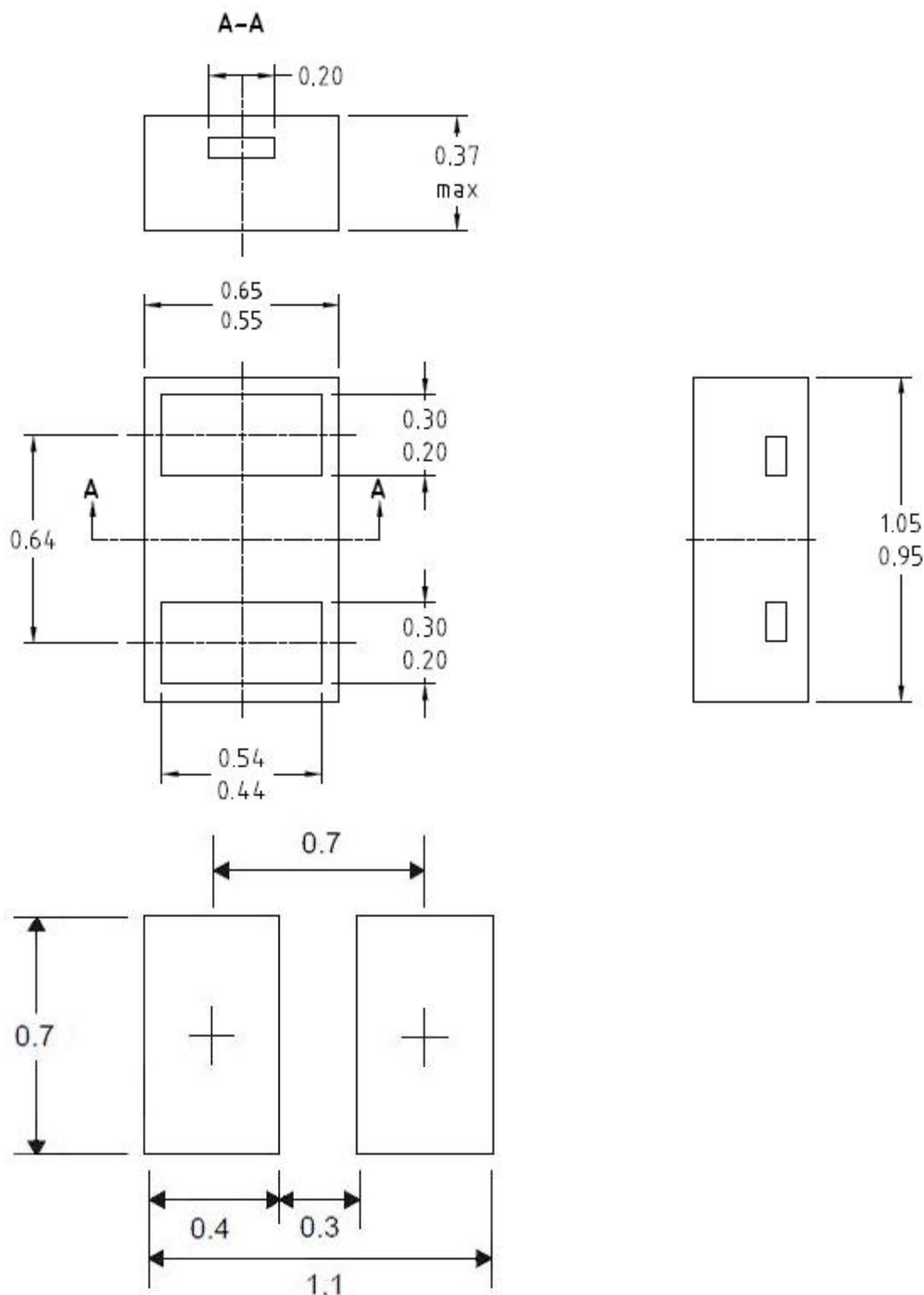


Figure 3- Power Derating Curve





### Disclaimer

Specifications are subject to change without notice.

The device characteristics and parameters in this data sheet can and do vary in different applications and actual device performance may vary over time.

Users should verify actual device performance in their specific applications.